FABRICATION OF TEMPERATURE MONITORING SYSTEM FOR ART CONSERVATION

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Introduction

- Currently, monitoring an artwork's temperature requires obtrusive, expensive equipment.
- Being able to produce low cost temperature monitoring systems is imperative for preserving art in all tiers of museums [1]. Resistance temperature detectors (RTDs) have a linear resistancetemperature relationship [2]. Aim: Create a RTD-based system that can wirelessly monitor artwork's temperature.

- Photolithography

- Process of exposing photoresist to UV light to etch patterns onto a substrate.
- Used to fabricate RTD and signal conditioning circuit.



Characterization

Given the linearity of the temperature-resistance relationship with RTDs, it is possible to characterize a linear equation relating them.

Water Bath Testing:

Coated RTD with liquid electrical tape, allowing submersion into water. Measured voltage across RTD in 0.5°C increments. Can determine resistance given voltage and constant current source.

Design and fabricate a resistance temperature detector (RTD) with a standardized reference resistance.

-**Objective**

- Materials AZ400K Acetone HMDS $\operatorname{Cr}_{7}^{+}$ AZP4110 FeCl₃ \bullet Glass or Silicon Buffer Oxide
- Photomask Photoresist Nickel Chromium Glass UV light etches away \bullet photoresist. Photoresist Nickel Chromium Glass Excess photoresist, nickel, and chromium etched away. Nickel

Results:

- V = 0.9263T + 33.926V = Voltage (mV)
 - T = Temperature (°C)
- $R^2 = 0.9996$
 - Extremely linear relationship



Etchant (BOE)

Substrate

Deionized Water





- 1. Spin coat a layer of HMDS onto wafer.
- 2. Spin coat a layer of AZP4110 onto wafer.
- 3. Apply UV light to react photoresist with light.
- 4. Develop photoresist into photomask pattern.
- 5. Etch away excess nickel and excess chromium.



Design

- **Parameters:**
 - Wire thickness = 200 nm.
 - Minimum line width = $200 \mu m$.
 - Spacing between wires = $200 \ \mu m$.
 - Minimum pad size = 25×25 mm = 625 mm².
- **Calculating Wire Length:**
 - R = Reference Resistance = 100Ω at $20 ^{\circ}$ C.
 - $\rho = \text{Resistivity} = 1.2 \times 10^{-7} \,\Omega \bullet \text{m}.$
- A = Cross-sectional area of wire.
- = thickness \times width = 40 μ m². • $R = \frac{\rho L}{A} \longrightarrow 100 = \frac{(1.2 \times 10^{-7})L}{40 \times 10^{-12}} \longrightarrow L = 3.\overline{33} \text{ cm.}$
- Sample Designs:

56 59 54 29 34 39 49 24 **Temperature (°C)**

-Next Steps

- Short Term:
 - Characterize newly fabricated RTDs with reference resistance of 100 Ω .
 - Utilize a more precise temperature control system \bullet and temperature monitoring system.
- Long Term:
 - Integrate a RTD and other sensor into system that can measure an artwork's environment temperature and wirelessly transmit data to a central hub.

FOUNDATION

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